

12V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
	15mΩ @ $V_{GS} = -4.5V$	-20A
-12V	20mΩ @ V _{GS} = -3.7V	-18A
	$30m\Omega$ @ $V_{GS} = -2.5V$	-16A
	40mΩ @ V _{GS} = -1.8V	-11A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Battery Management Application
- Power Management Functions
- DC-DC Converters

Features

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low On-Resistance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

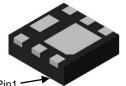
Mechanical Data

- Case: U-DFN2020-6 (Type F)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 🚱
- Weight: 0.007 grams (Approximate)

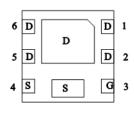
U-DFN2020-6 (Type F)



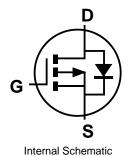
Top View



Bottom View



Pin Out Bottom View



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP1012UFDF-7	U-DFN2020-6 (Type F)	3,000/Tape & Reel
DMP1012UFDF-13	U-DFN2020-6 (Type F)	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



PF = Product Type Marking Code YM = Date Code Marking Y = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Year	2018		2019	2020		2021	2022		2023	2024		2025
Code	F		G	Н		I	J		K	L		M
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit			
Drain-Source Voltage	V_{DSS}	-12	V			
Gate-Source Voltage	V_{GSS}	±8	V			
Continuous Drain Current V _{GS} = -4.5V (Note 10)	Steady State	$T_C = +25$ °C $T_C = +70$ °C	Ι _D	-20 -16	Α	
	I _D	-12.6	Α			
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	-55	Α			
Maximum Body Diode Continuous Current (Note 6)	Is	-2.8	Α			
Avalanche Current (Note 7), L = 0.1mH	I _{AS}	-21	Α			
Avalanche Energy (Note 7,) L = 0.1mH	E _{AS}	22	mJ			

Thermal Characteristics

Characteristic		Symbol	Value	Unit	
Total Power Discipation (Note 5)	$T_A = +25^{\circ}C$	D	0.72	W	
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	P_{D}	0.46	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	р	172	°C/W	
Thermal Resistance, Junction to Ambient (Note 3)	t<5s	$R_{\theta JA}$	130	C/VV	
Total Power Dissipation (Note 6)	$T_A = +25$ °C	Pn	2.11	W	
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	PD	1.36		
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	7	59	°C/W	
Thermal Resistance, Junction to Ambient (Note o)	t<5s	$R_{\theta JA}$	44		
Thermal Resistance, Junction to Case (Note 6)	Steady State	$R_{ heta JC}$	9.0		
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	-12	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μA	$V_{DS} = -10V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	-0.3	-0.5	-0.9	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
			11	15		$V_{GS} = -4.5V, I_D = -5A$
Static Drain-Source On-Resistance	D-s/s/		12	20	mΩ	$V_{GS} = -3.7V$, $I_{D} = -5A$
Static Dialif-Source Off-Resistance	R _{DS(ON)}		15	30	11122	$V_{GS} = -2.5V$, $I_D = -4A$
			20	40		$V_{GS} = -1.8V, I_{D} = -1A$
Diode Forward Voltage	V_{SD}	_	-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -10A$
DYNAMIC CHARACTERISTICS (Note 9)						_
Input Capacitance	C _{iss}	_	1344	_		VDS = -10V, VGS = 0V,
Output Capacitance	Coss	_	342	_	pF	f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	297	_		1 - 1.01/11/2
Gate Resistance	R_{g}	_	15	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	19.5	_		
Total Gate Charge (V _{GS} = -8V)	Qg	_	31	_	nC	V _{DS} = -6V. I _D = -10A
Gate-Source Charge	Q _{gs}	_	2.1	_	IIC	V _{DS} = -6V, I _D = -10A
Gate-Drain Charge	Q_{gd}	_	7.9	_		
Turn-On Delay Time	t _{D(ON)}	_	6.0	_		
Turn-On Rise Time	t _R	_	32	_		$V_{DS} = -6V, V_{GS} = -4.5V,$
Turn-Off Delay Time	t _{D(OFF)}	_	71	_	ns	$R_g = 1\Omega$, $I_D = -8A$
Turn-Off Fall Time	t _F	_	85	_		
Reverse Recovery Time	t _{RR}	_	46	_	ns	1 404 11/11 5004/
Reverse Recovery Charge	Q _{RR}		44	_	nC	I _F = -12A, di/dt = 500A/μs

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

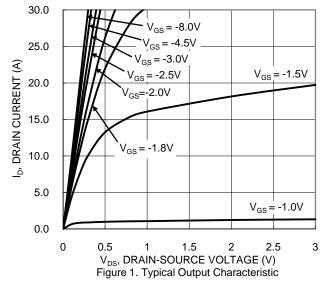
7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.

8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.

10. Package limited. Notes:





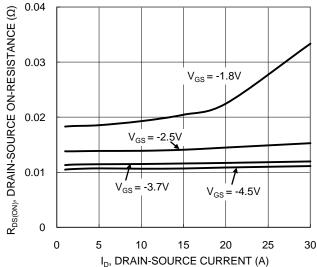


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

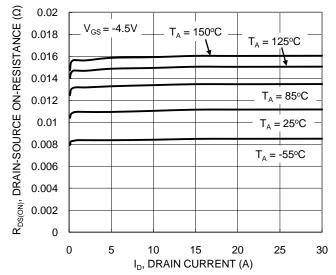


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

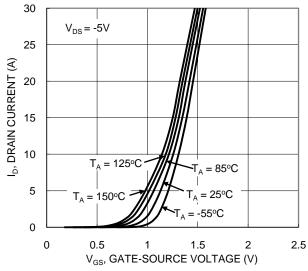


Figure 2. Typical Transfer Characteristic

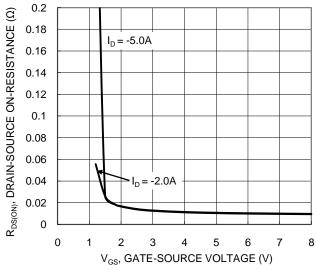


Figure 4. Typical Transfer Characteristic

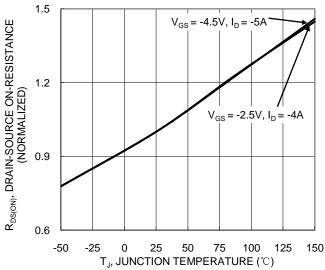
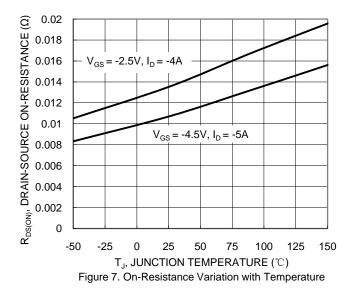
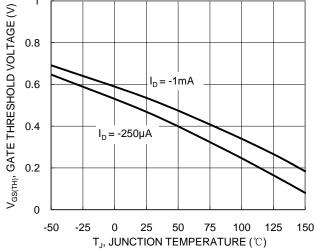
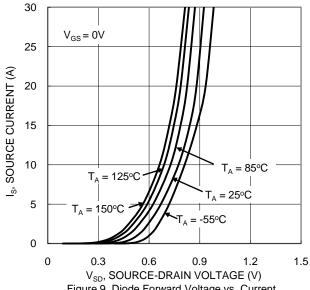


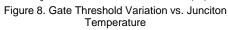
Figure 6. On-Resistance Variation with Temperature

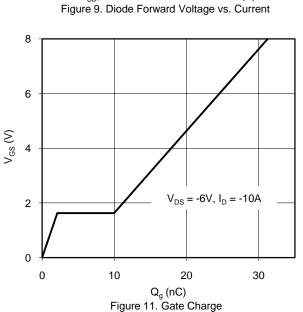


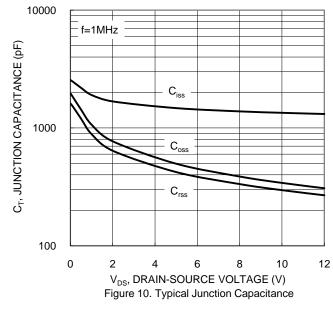


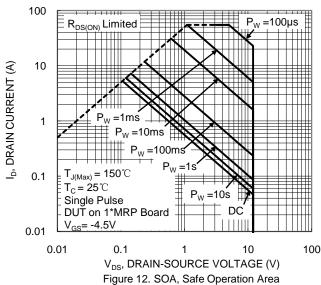














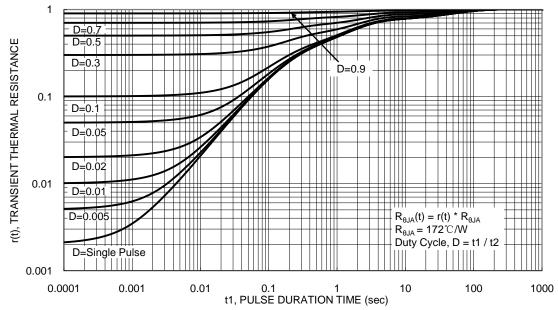


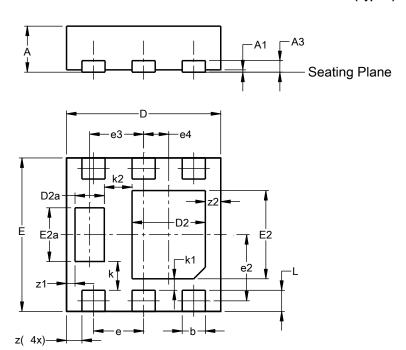
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

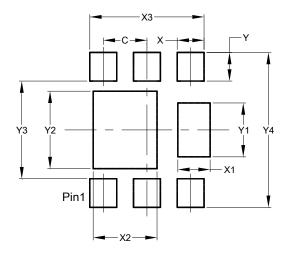


U-DFN2020-6								
(Type F)								
Dim	Min	Min Max Typ						
Α	0.57 0.63 0.60							
A1	0.00 0.05 0.03							
A3	-	-	0.15					
b	0.25	0.35	0.30					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
D2a	0.33	0.43	0.38					
Е	1.95	1.95 2.05 2.00						
E2	1.05 1.25 1.15							
E2a	0.65 0.75 0.70							
е		0.65 BS						
e2	C).863 BS	SC					
е3		0.70 BSC						
e4		0.325 BSC						
k	0.37 BSC							
k1	0.15 BSC							
k2	0.36 BSC							
L	0.225 0.325 0.275							
Z	0.20 BSC							
z1	0.110 BSC							
z2	0.20 BSC							
All Dimensions in mm								

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	value
Dilliensions	(in mm)
С	0.650
Х	0.400
X1	0.480
X2	0.950
Х3	1.700
Υ	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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